SCF 9200
Copper Content Thermal Compound

Description

SCF 9200 copper content thermal compound blended with excellent heat-conductive copper fillers. The low bleed properties of this improved compound assure lasting for heat transfer coupling.

SCF 9200 is an effective thermal coupler for any heat sink device where efficient cooling is required, such as CPU power transistor, and SCRs to heat sink or chassis. This grease-like compound will not dry out, harden, or melt even after long term exposure to temperatures up to 150°C.

SCF 9200 contains no lead or other harmful heavy metal salts and will not irritate skin.

Features

※ Grease –like consistency
※ Gold color
※ Low bleed
※ Very stable at elevated temperatures
※ Excellent thermal resistance and high thermal conductivity
※ Efficient thermal coupler
※ Effective and positive heat sink sealers and heat transfer agent

Typical Properties

There values are not intended for use in preparing specifications.

Color	Gold
Copper Content, %	25
Metal Oxide %	10
Penetration	400 ~ 450
Bleed, percent after 25 hrs at 150°C	0.3 ~ 0.5
Evaporation, percent after 24 hrs at 150°C	0.3 ~ 0.8
Thermal Conductivity, W/m · K	4.5
Thermal Resistance, °C-in^2 / W	0.18